Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**Top Material: Al**

**Backside Material: Si Ni**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Leave FLOATING**

**Mask Ref: CIC01749**

**APPROVED BY: DK DIE SIZE .142” X .172” DATE: 6/16/22**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: ADS574**

**DG 10.1.2**

#### Rev B, 7/19/02